



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2015-05-18
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Laurent TOSI	<b>Representative Title</b>	MMS MD CHAMPION
<b>Representative Phone *</b>	33 442 685 795	<b>Representative Email *</b>	<a href="mailto:laurent.tosi@st.com">laurent.tosi@st.com</a>
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/online_tech_support.html">http://www.st.com/web/en/support/online_tech_support.html</a>		

**Uncertainty Statement**


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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32F103C8T6	925B*410XXX2	A	959	2015-05-18
Amount	UoM	Unit type	ST ECOPACK Grade	
180,00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
2	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	NiPdAu	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	7x7x1.4	48	L bend	
Comment	LQFP 48L BODY 7x7x1.4 FOOT PRINT 1.0			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-16th December 2013				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	9258*410XXX2						
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)	
die (s)	Other inorganic materials	10,192	mg	supplier	die	Silicon (Si)	7440-21-3		9,860	mg	967425	54778	
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0,029	mg	2845	161	
die (s)				supplier	metallization	Copper (Cu)	7440-50-8		0,029	mg	2845	161	
die (s)				supplier	metallization	Titanium (Ti)	7440-32-6		0,060	mg	5887	333	
die (s)				supplier	metallization	Tungsten (W)	7440-33-7		0,012	mg	1177	67	
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0,019	mg	1864	106	
die (s)				supplier	passivation	Indium Tin oxide ( In2O3.SnO2 )	50926-11-9		0,183	mg	17955	1017	
Lead-frame	Other inorganic materials	69,913	mg	supplier	alloy	Copper (Cu)	7440-50-8		67,256	mg	962000	373644	
Lead-frame				supplier	alloy	Nickel (Ni)	7440-02-0		2,097	mg	30000	11652	
Lead-frame				supplier	alloy	Silicium (Si)	7440-21-3		0,454	mg	6500	2525	
Lead-frame				supplier	alloy	Magnesium (Mg)	7439-95-4		0,105	mg	1500	583	
Lead-frame Coating	Other inorganic materials	0,403	mg	supplier	coating	Nickel (Ni)	7440-02-0		0,369	mg	914840	2048	
Lead-frame Coating				supplier	coating	Palladium (Pd)	7440-05-3		0,012	mg	29660	66	
Lead-frame Coating				supplier	coating	Gold (Au)	7440-57-5		0,011	mg	27750	62	
Lead-frame Coating				supplier	coating	Silver (Ag)	7440-22-4		0,011	mg	27750	62	
Die Attach	Other inorganic materials	1,954	mg	supplier	glue or soft solder	Silver (Ag)	7440-22-4		1,505	mg	770000	8359	
Die Attach				supplier	glue or soft solder	Epoxy Cresol Novolak	29690-82-2		0,442	mg	226000	2454	
Die Attach				supplier	glue or soft solder	1-isopropyl-2,2-dimethyltrimethylene diisobutyl	6846-50-0		0,008	mg	4000	43	
Wires	Other inorganic materials	0,913	mg	supplier	Bonding wire	Gold (Au)	7440-57-5		0,913	mg	1000000	5074	
Encapsulation	Other inorganic materials	96,623	mg	supplier	Moulding Compound	Solid Epoxy Resin	na		6,786	mg	70233	37700	
Encapsulation				supplier	Moulding Compound	Phenol Resin	na		4,847	mg	50166	26929	
Encapsulation				supplier	Moulding Compound	Silica, vitreous	60676-86-0		84,214	mg	871574	467854	
Encapsulation				supplier	Moulding Compound	Carbon-black	1333-86-4		0,485	mg	5017	2693	
Encapsulation				supplier	Moulding Compound	Bismuth (Bi)	7440-69-9		0,145	mg	1505	808	
Encapsulation				supplier	Bismuth/Bismuth Compounds	Bismuth	7440-69-9		0,145	mg	1505	808	
Finishing	Other inorganic materials	0,003	mg	supplier	connections coating	Nickel (Ni)	7440-02-0		0,002	mg	914840	13	
Finishing				supplier	connections coating	Palladium (Pd)	7440-05-3		0,000	mg	29660	0	
Finishing				supplier	connections coating	Gold (Au)	7440-57-5		0,000	mg	27750	0	
Finishing				supplier	connections coating	Silver (Ag)	7440-22-4		0,000	mg	27750	0	